

14-Sep-2011

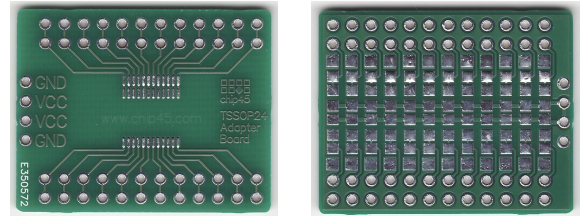
Article No.: PCB-SMT-TSSOP24

The TSSOP24 SMT adapter PC-board provides a footprint for SSOP and TSSOP IC packages from (T)SSOP4 up to (T)SSOP24 with narrow and wide body and pin spacing of 0.635mm (25mil). It can also be used to assemble more than one device, e.g. like twice a TSSOP8 package or similar.

Top Side Footprint and Pads

The pictures on the right show the top and bottom side of the TSSOP24 SMT adapter PC-board.

Each pad of the TSSOP footprint is connected to one of the standard 2.54mm (100mil, 1/10") pin headers on the upper and lower end. The pin headers are double row and the two rows are interconnected 1:1, to provide an additional spot for each device signal for connecting a jumper cable and hooking up a measurement clip. This is an advantage over single row designs, since it's often necessary to connect more than one cable to one signal. When used in a solderless breadboard, just use only one of the two rows on each end.



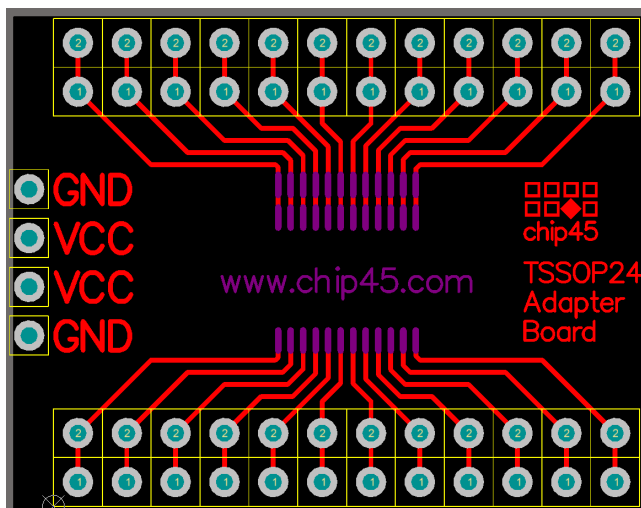
Additional VCC and GND pads are available on the left. These pads are especially useful for connecting one or more device pins to VCC or GND, either directly or through an smt capacitor or resistor on the back side.

Back Side Footprint Matrix

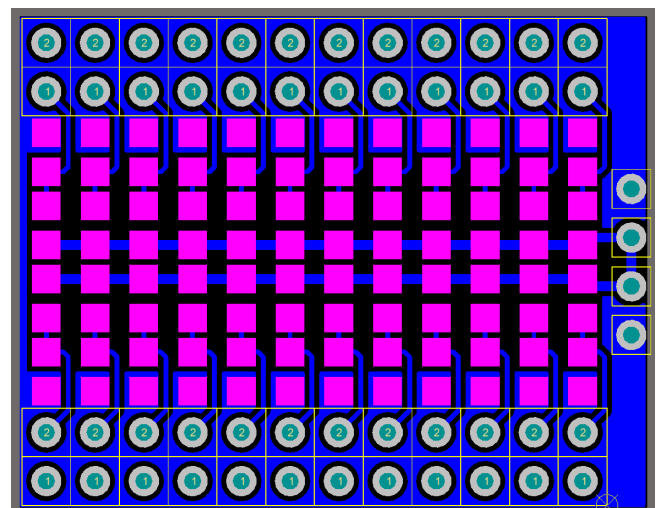
The back side of the PCB provides two 2-pad footprints on each device signal. One pad of each footprint is connected to the device signal and the other pad is connected to VCC or GND respectively. The footprints can be used to either connect the signal directly to VCC or GND (by closing one footprint with solder like a jumper) or to insert a resistor (e.g. pull-up or pull-down resistor), a capacitor (e.g. 100nF bypass capacitor) or an inductor (e.g. filtering of an analog VCC) between the signal and VCC or GND. The picture on the right shows the bottom side of the PCB with a mini-melf pull-down resistor, a 0603 pull-up resistor, a 0805 bypass capacitor to GND, a mini-melf diode and a solder spot (left to right).



Layout Details Top and Bottom Side



PCB Top Layer



PCB Bottom Layer

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